

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	22	Yuan-ping.in.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 14:15
2	IS&R	L2	11	(("20010009301") or ("5942794") or ("5157457") or ("6483178") or ("6424024") or ("6400004")) .PN.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 16:59
3	IS&R	L3	2	("5157475") .PN.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 15:04
4	IS&R	L4	1	("6548328") .PN.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 15:04
5	IS&R	L5	2	("5752182") .PN.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 17:04

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	IS&R	L6	2	("6399415").PN.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 17:05
7	BRS	L7	16	(seal\$4 adj resin) near2 magnetic	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 17:59
8	BRS	L8	170	multi adj substrate	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 18:24
9	IS&R	L9	4	((("6399415") or ("5741729"))).PN.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 18:24

-	7	Bayan-jaime.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/04/23 13:22
-	26	("5157475" "5157480" "5367196" "5454905" "5494207" "5508556" "5521429" "5596231" "5623123" "5656550" "5741729" "5844315" "5854511" "5866948" "5981314" "5990545" "6013946" "6060774" "6060778" "6093960" "6130473" "6133070" "6177288" "6188130" "6201292" "6215179").PN.		2003/04/23 13:09
-	170	ueno-yutaka.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 14:00
-	247	257/711,684,730-731.ccls. and substrate and (groove concave trench\$4 recess\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 15:13
-	676	257/782-784,787-789,796.ccls. and substrate and (groove concave trench\$4 recess\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 14:21
-	34	257/782-784,787-789,796.ccls. and substrate with (metal adj layer) and (groove concave trench\$4 recess\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 14:26
-	5023	substrate with (metal adj layer) and (groove concave trench\$4 recess\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 14:44
-	1909	substrate with (metal adj layer) and (groove concave trench\$4 recess\$4) and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 14:46
-	3832	substrate with (metal adj layer) and (groove concave trench\$4 recess\$4) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 15:03
-	724	substrate with (metal adj layer) with (groove concave trench\$4 recess\$4) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 15:05
-	4	257/711,684,730-731.ccls. and (multilayer adj substrate) and (groove concave trench\$4 recess\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 15:16
-	427	(multilayer adj substrate) and (groove concave trench\$4 recess\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 15:18

-	36	((("5633204") or ("5508561") or ("6259161") or ("6288851") or ("6278190") or ("6344682") or ("6184061") or ("5986336") or ("5959353") or ("6270202") or ("5900582") or ("5969463") or ("5910699") or ("5925973") or ("5724726") or ("5763829") or ("5281818") or ("5291484") or ("4831636"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:35
-	429	(reaction adj layer) and laminat\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 16:03
-	66	(reaction adj layer) and laminat\$4 and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 16:03
-	17	438/615.ccls. and laminat\$4 and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 16:10
-	580	438/613-617.ccls. and press\$4 and heat\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 16:19
-	488	438/613-617.ccls. and press\$4 and heat\$4 and (bump ball) and (chip die IC substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 16:23
-	0	((masamoto adj tago) (Yoshihiro adj tomita)) and press\$4 and heat\$4 and (bump ball) and (chip die IC substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 17:02
-	5	tago-masamoto.in. and heat\$4 and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 17:11
-	2	tago-masamoto.in. and Tomita-yoshihiro.in. and heat\$4 and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 17:12
-	27	Tomita-yoshihiro.in. and heat\$4 and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/10 15:18
-	24	((("5229647") or ("5418687") or ("5440241") or ("5506383") or ("5682062") or ("5685885") or ("5742100") or ("5767575") or ("5892288") or ("5973396") or ("5990546") or ("6004867"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/10 15:56
-	3	("3171643").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 11:47
-	2	("2002170919").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 11:47

-	1	irradiating adj radical adj fluorine	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:26
-	1	irradiat\$4 adj radical adj fluorine	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:26
-	0	activating and sputtering	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:27
-	9	activat\$4 and sputtering	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:29
-	0	activat\$4 with sputtering	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:29
-	0	sputterr\$4 and (reduction adj gas)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:30
-	0	sputterr\$4 and (reduct\$4 adj gas)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:40
-	2	("2002110726").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:56
-	133	multi-layer and solder and intermetallic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:04
-	1603	solder and intermetallic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:04
-	581	solder and intermetallic and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:05
-	310	solder and intermetallic and (bump ball) and press\$4 and (heat\$4 reflow\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:18
-	6	((("6344696") or ("5633204") or ("5508561"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:27

L Number	Hits	Search Text	DB	Time stamp
-	4	257/737-738.ccls. and (bump ball) and (supersonic adj wave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 13:37
-	1	257/779.ccls. and (bump ball) and (supersonic adj wave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 13:38
-	0	257/685-686.ccls. and (bump ball) and (supersonic adj wave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 13:39
-	577	257/685-686.ccls. and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 13:43
-	0	257/685-686.ccls. and (supersonic adj wave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 13:44
-	128	257/685-686.ccls. and laminat\$4 and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 13:54
-	157	438/613-617.ccls. and laminat\$4 and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 16:18
-	90	438/612.ccls. and laminat\$4 and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:14
-	419	438/612.ccls. and ((irrfaiating adj radical adj fluorine) (reduction adj gas) sputter\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:16
-	136	438/612.ccls. and ((irrfaiating adj radical adj fluorine) (reduction adj gas) sputter\$4) and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:22
-	1	(atomic adj beam) with (inactive adj gas adj excited) near3 plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:23
-	1	(atomic adj beam) with (inactive adj gas adj excited) with plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:24
-	1	(atomic adj beam) and (inactive adj gas adj excited) and plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:25